Amendments to the Specification:

Please replace paragraphs 21, 33 and 34, with the following rewritten paragraphs, respectively:

Page 6, paragraph 21:

[0021] Figure 1 shows a ~~liner~~ linear belt processing surface of a typical CMP processing system.

Pages 7 and 8, paragraphs 33 and 34:

[0033] Figure 1 shows a ~~liner~~ linear belt processing surface 10 of a typical CMP processing system. Processing belt 12 includes rigid and flexible processing belts 12 traveling around rollers (not shown) in direction 14. A wafer 16 is typically applied to a center region of processing belt 12 with a pressure and rotated in, by way of example, direction 18. In Figure 1, processing belt 12 is shown divided into ten zones 20a-20j across the surface of processing belt 12, and wafer 16 is shown divided into four regions 22a-22d from the edge region 22a of the wafer 16 to the center region 22d of the wafer 16. The processing zones 20a-20j and the wafer regions 22a-22d are exemplary only, and may be represented by more or fewer zones and regions in other processing configurations, processing apparatus, semiconductor wafer sizes, and the like.

[0034] As wafer 16 is rotated in direction 18, wafer regions 22a-22d rotate through a plurality of processing belt zones 20a-20j. As can be appreciated from Figure 1, edge region 22a travels through more processing belt zones 20a-20j than center region 22d. As center region travels through processing belt zones 20e and 20f, edge region 22a travels through processing belt zones 20b, 20c, 20d, 20e, 20f, 20g, 20h, and 20i. The center processing belt zones 20e and 20f contact greater than three times the wafer surface area than do processing belt zones

20b and 20i. Further, temperature variations across processing belt zones 20a-20j have a much more significant impact on wafer edge region 22a traveling through a greater number of processing belt zones 20b-20i than on wafer center region 22d traveling ~~though~~ through belt processing zones 20e and 20f.